

## 6A Single High-Speed, CMOS Power MOSFET Driver

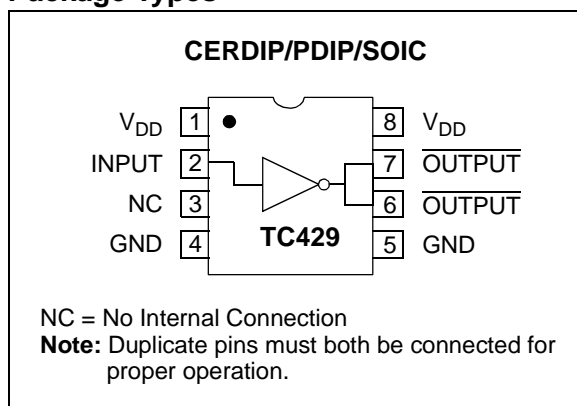
### Features

- High Peak Output Current: 6A
- Wide Input Supply Voltage Operating Range:
  - 7V to 18V
- High-Impedance CMOS Logic Input
- Logic Input Threshold Independent of Supply Voltage
- Low Supply Current:
  - With Logic '1' Input – 5 mA max.
  - With Logic '0' Input – 0.5 mA max.
- Output Voltage Swing Within 25 mV of Ground or  $V_{DD}$
- Short Delay Time: 75 nsec max
- Available in the Space-Saving 8-Pin SOIC Package.
- High Capacitive Load Drive Capability:
  - $t_{RISE}, t_{FALL} = 35$  nsec max with  $C_{LOAD} = 2500$  pF

### Applications

- Switch-Mode Power Supplies
- CCD Drivers
- Pulse Transformer Drive
- Class D Switching Amplifiers

### Package Types



### General Description

The TC429 is a high-speed, single output, CMOS-level translator and driver. Designed specifically to drive highly capacitive power MOSFET gates, the TC429 features a 2.5Ω output impedance and 6A peak output current drive.

A 2500 pF capacitive load will be driven to 18V in 25 nsec. The rapid switching times with large capacitive loads minimize MOSFET switching power losses.

A TTL/CMOS input logic level is translated into an output voltage swing that equals the supply voltage and will swing to within 25 mV of ground or  $V_{DD}$ . Input voltage swing may equal the supply voltage. Logic input current is under 10 μA, making direct interface to CMOS/bipolar switch-mode power supply controllers easy. Input "speed-up" capacitors are not required.

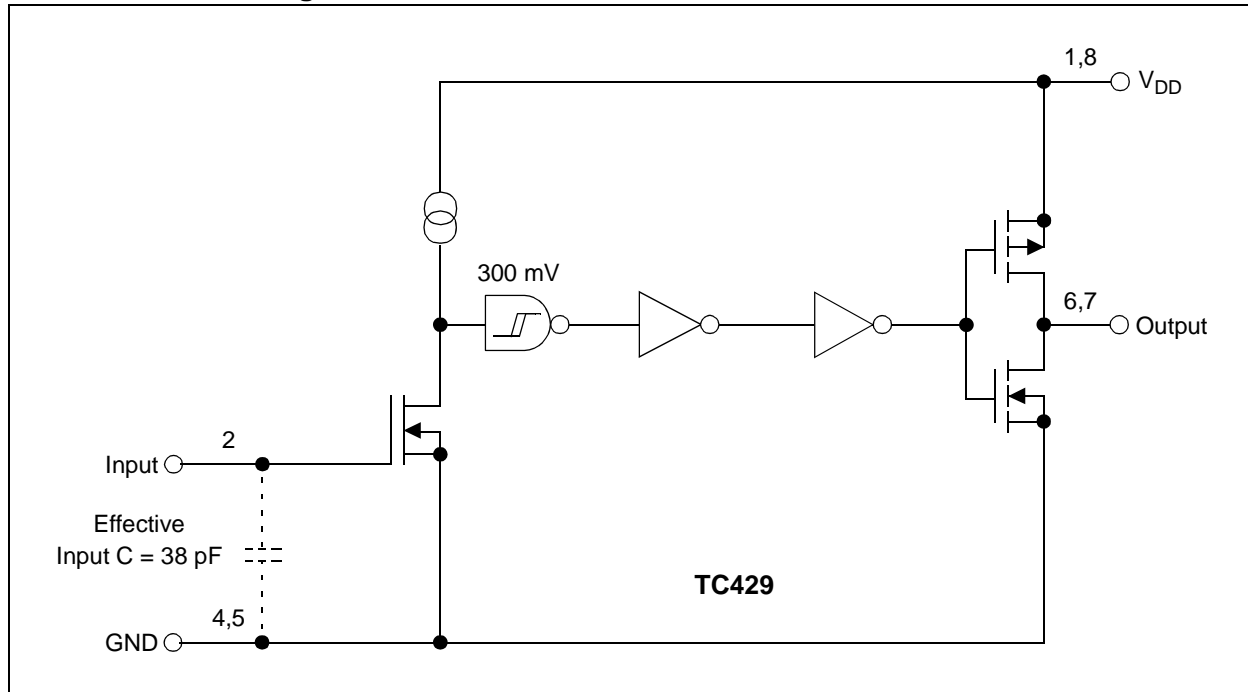
The CMOS design minimizes quiescent power supply current. With a logic '1' input, power supply current is 5 mA maximum and decreases to 0.5 mA for logic '0' inputs.

For dual output MOSFET drivers, see the TC426/TC427/TC428 (DS21415), TC4426/TC4427/TC4428 (DS21422) and TC4426A/TC4427A/TC4428A (DS21423) data sheets.

For non-inverting applications, or applications requiring latch-up protection, see the TC4420/TC4429 (DS21419) data sheet.

# TC429

## Functional Block Diagram



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

Supply Voltage .....	+20V
Input Voltage, Any Terminal .....	$V_{DD} + 0.3V$ to $GND - 0.3V$
Power Dissipation ( $T_A \leq 70^\circ C$ )	
PDIP .....	730 mW
CERDIP .....	800 mW
SOIC .....	470 mW
Storage Temperature Range .....	$-65^\circ C$ to $+150^\circ C$
Maximum Junction Temperature, $T_J$ .....	$+150^\circ C$

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

### PIN FUNCTION TABLE

Symbol	Description
$V_{DD}$	Supply input, 7V to 18V
INPUT	Control input. TTL/CMOS compatible logic input
NC	No connection
GND	Ground
GND	Ground
$\overline{\text{OUTPUT}}$	CMOS push-pull, common to pin 7
$\overline{\text{OUTPUT}}$	CMOS push-pull, common to pin 6
$V_{DD}$	Supply input, 7V to 18V

## DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = +25^\circ C$ with $7V \leq V_{DD} \leq 18V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Input</b>						
Logic '1', High Input Voltage	$V_{IH}$	2.4	1.8	—	V	
Logic '0', Low Input Voltage	$V_{IL}$	—	1.3	0.8	V	
Input Current	$I_{IN}$	-10	—	10	$\mu A$	$0V \leq V_{IN} \leq V_{DD}$
<b>Output</b>						
High Output Voltage	$V_{OH}$	$V_{DD} - 0.025$	—	—	V	
Low Output Voltage	$V_{OL}$	—	—	0.025	V	
Output Resistance	$R_O$	—	1.8	2.5	$\Omega$	$V_{IN} = 0.8V$ , $V_{OUT} = 10 mA$ , $V_{DD} = 18V$ $V_{IN} = 2.4V$ , $V_{OUT} = 10 mA$ , $V_{DD} = 18V$
Peak Output Current	$I_{PK}$	—	6.0	—	A	$V_{DD} = 18V$ , <b>Figure 4-4</b>
Latch-Up Protection Withstand Reverse Current	$I_{REV}$	—	0.5	—	A	Duty cycle $\leq 2\%$ , $t \leq 300 \mu sec$ , $V_{DD} = 16V$
<b>Switching Time (Note 1)</b>						
Rise Time	$t_R$	—	23	35	nsec	$C_L = 2500 pF$ , <b>Figure 4-1</b>
Fall Time	$t_F$	—	25	35	nsec	$C_L = 2500 pF$ , <b>Figure 4-1</b>
Delay Time	$t_{D1}$	—	53	75	nsec	<b>Figure 4-1</b>
Delay Time	$t_{D2}$	—	60	75	nsec	<b>Figure 4-1</b>
<b>Power Supply</b>						
Power Supply Current	$I_S$	—	3.5	5.0	mA	$V_{IN} = 3V$ $V_{IN} = 0V$

**Note 1:** Switching times ensured by design.

# TC429

## DC ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, over operating temperature range with $7V \leq V_{DD} \leq 18V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Input</b>						
Logic '1', High Input Voltage	$V_{IH}$	2.4	—	—	V	
Logic '0', Low Input Voltage	$V_{IL}$	—	—	0.8	V	
Input Current	$I_{IN}$	-10	—	10	$\mu A$	$0V \leq V_{IN} \leq V_{DD}$
<b>Output</b>						
High Output Voltage	$V_{OH}$	$V_{DD} - 0.025$	—	—	V	
Low Output Voltage	$V_{OL}$	—	—	0.025	V	
Output Resistance	$R_O$	—	—	5.0	$\Omega$	$V_{IN} = 0.8V$ , $V_{OUT} = 10\text{ mA}$ , $V_{DD} = 18V$
		—	—	5.0		$V_{IN} = 2.4V$ , $V_{OUT} = 10\text{ mA}$ , $V_{DD} = 18V$
<b>Switching Time (Note 1)</b>						
Rise Time	$t_R$	—	—	70	nsec	$C_L = 2500\text{ pF}$ , <b>Figure 4-1</b>
Fall Time	$t_F$	—	—	70	nsec	$C_L = 2500\text{ pF}$ , <b>Figure 4-1</b>
Delay Time	$t_{D1}$	—	—	100	nsec	<b>Figure 4-1</b>
Delay Time	$t_{D2}$	—	—	120	nsec	<b>Figure 4-1</b>
<b>Power Supply</b>						
Power Supply Current	$I_S$	—	—	12	mA	$V_{IN} = 3V$
		—	—	1.0		$V_{IN} = 0V$

**Note 1:** Switching times ensured by design.

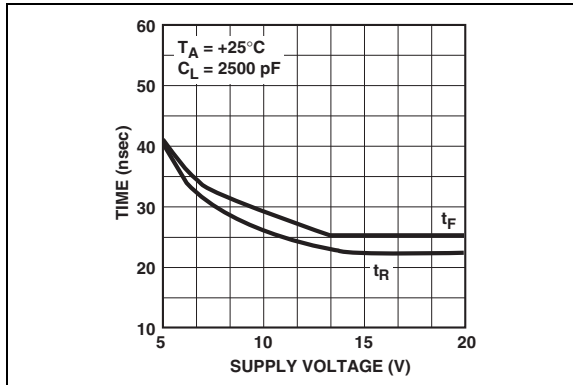
## TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = +25^\circ C$ with $7V \leq V_{DD} \leq 18V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Temperature Ranges</b>						
Specified Temperature Range (C)	$T_A$	0	—	+70	$^\circ C$	
Specified Temperature Range (E)	$T_A$	-40	—	+85	$^\circ C$	
Specified Temperature Range (M)	$T_A$	-55	—	+125	$^\circ C$	
Maximum Junction Temperature	$T_J$	—	—	+150	$^\circ C$	
Storage Temperature Range	$T_A$	-65	—	+150	$^\circ C$	
<b>Package Thermal Resistances</b>						
Thermal Resistance, 8L-CERDIP	$\theta_{JA}$	—	150	—	$^\circ C/W$	
Thermal Resistance, 8L-PDIP	$\theta_{JA}$	—	125	—	$^\circ C/W$	
Thermal Resistance, 8L-SOIC	$\theta_{JA}$	—	155	—	$^\circ C/W$	

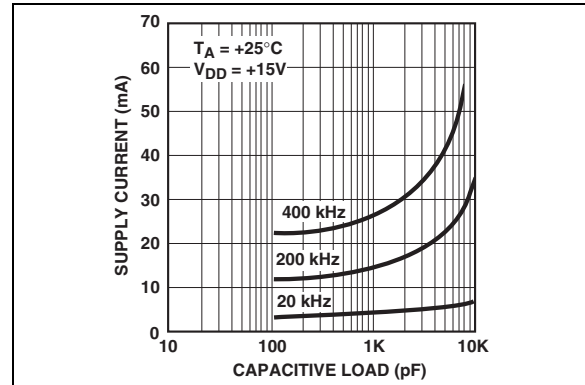
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

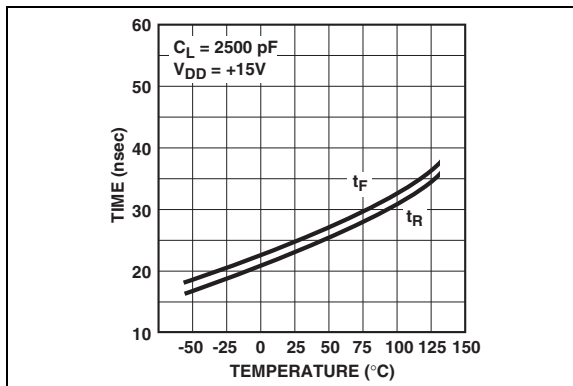
**Note:** Unless otherwise indicated,  $T_A = +25^\circ\text{C}$  with  $7\text{V} \leq V_{DD} \leq 18\text{V}$ .



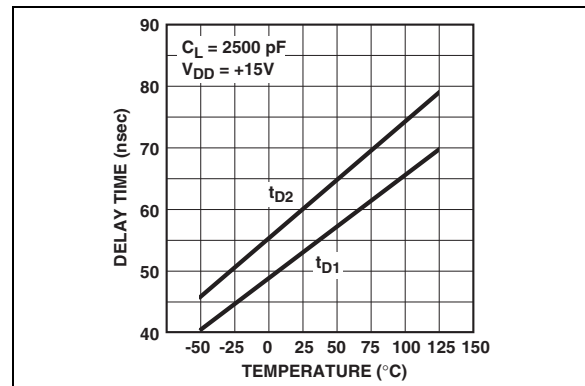
**FIGURE 2-1:** Rise/Fall Times vs. Supply Voltage.



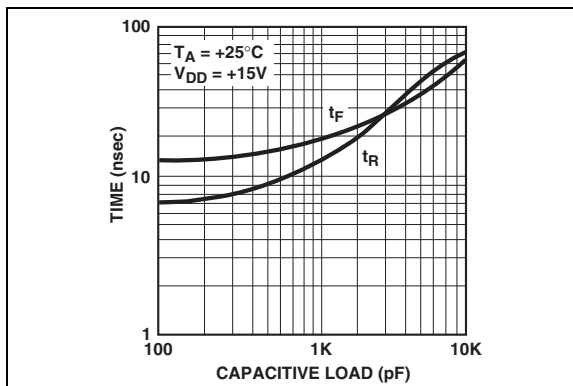
**FIGURE 2-4:** Supply Current vs. Capacitive Load.



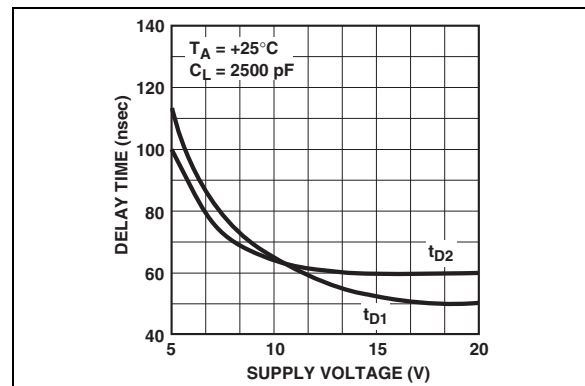
**FIGURE 2-2:** Rise/Fall Times vs. Temperature.



**FIGURE 2-5:** Delay Times vs. Temperature.



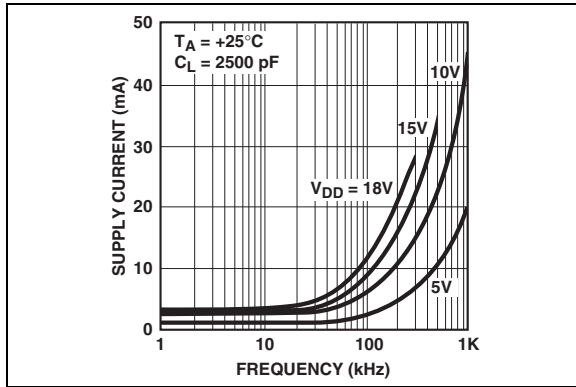
**FIGURE 2-3:** Rise/Fall Times vs. Capacitive Load.



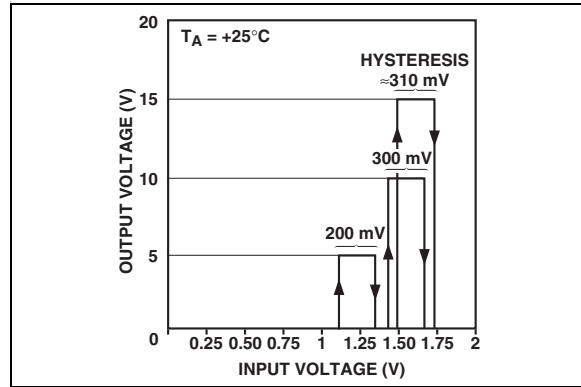
**FIGURE 2-6:** Delay Times vs. Supply Voltage.

# TC429

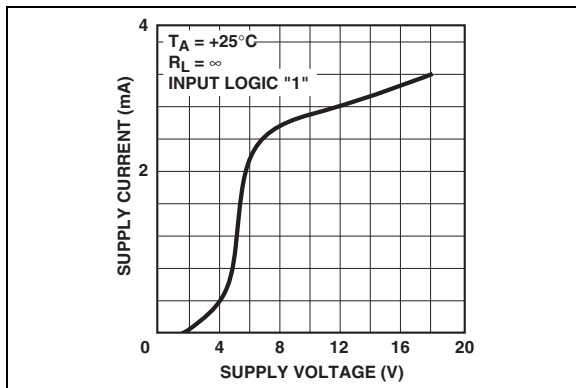
**Note:** Unless otherwise indicated,  $T_A = +25^\circ\text{C}$  with  $7\text{V} \leq V_{DD} \leq 18\text{V}$ .



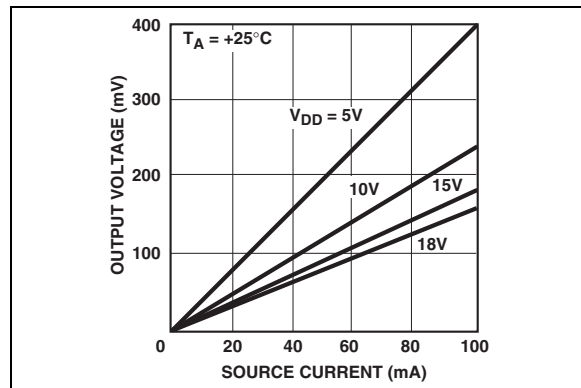
**FIGURE 2-7:** Supply Current vs. Frequency.



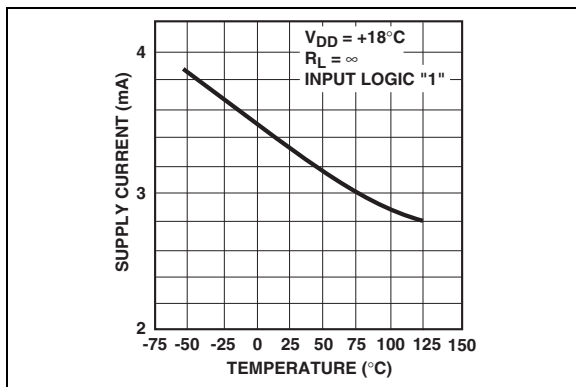
**FIGURE 2-10:** Voltage Transfer Characteristics.



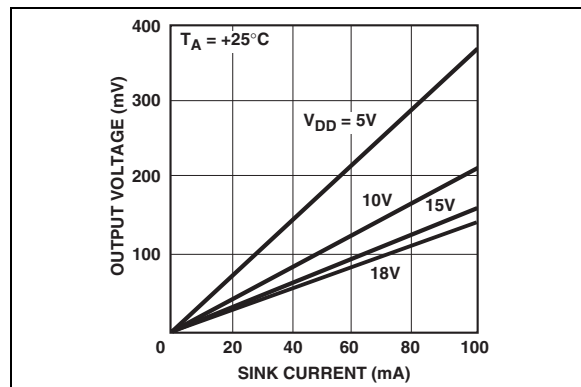
**FIGURE 2-8:** Supply Current vs. Supply Voltage.



**FIGURE 2-11:** High Output Voltage ( $V_{DD} - V_{OH}$ ) vs. Output Source Current.



**FIGURE 2-9:** Supply Current vs. Temperature.



**FIGURE 2-12:** Low Output Voltage vs. Output Sink Current.

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

**TABLE 3-1: PIN FUNCTION TABLE**

Pin No.	Symbol	Description
1	$V_{DD}$	Supply input, 7V to 18V
2	INPUT	Control input. TTL/CMOS compatible logic input
3	NC	No connection
4	GND	Ground
5	GND	Ground
6	$\overline{\text{OUTPUT}}$	CMOS push-pull output, common to pin 7
7	$\overline{\text{OUTPUT}}$	CMOS push-pull output, common to pin 6
8	$V_{DD}$	Supply input, 7V to 18V

### 3.1 Supply Input ( $V_{DD}$ )

The  $V_{DD}$  input is the bias supply for the MOSFET driver and is rated for 7.0V to 18V with respect to the ground pin. The  $V_{DD}$  input should be bypassed to ground with a local ceramic capacitor. The value of the capacitor should be chosen based on the capacitive load that is being driven. A value of 1.0  $\mu\text{F}$  is suggested.

### 3.2 Control Input (INPUT)

The MOSFET driver input is a high-impedance, TTL/CMOS compatible input. The input also has 300 mV of hysteresis between the high and low thresholds that prevents output glitching even when the rise and fall time of the input signal is very slow.

### 3.3 CMOS Push-Pull Output (OUTPUT)

The MOSFET driver output is a low-impedance, CMOS push-pull style output, capable of driving a capacitive load with 6.0A peak currents.

### 3.4 Ground (GND)

The ground pins are the return path for the bias current and for the high peak currents that discharge the load capacitor. The ground pins should be tied into a ground plane or have very short traces to the bias supply source return.

### 3.5 No Connect (NC)

No connection.

## 4.0 APPLICATIONS INFORMATION

### 4.1 Supply Bypassing

Charging and discharging large capacitive loads quickly requires large currents. For example, charging a 2500 pF load to 18V in 25 nsec requires a 1.8A current from the device's power supply.

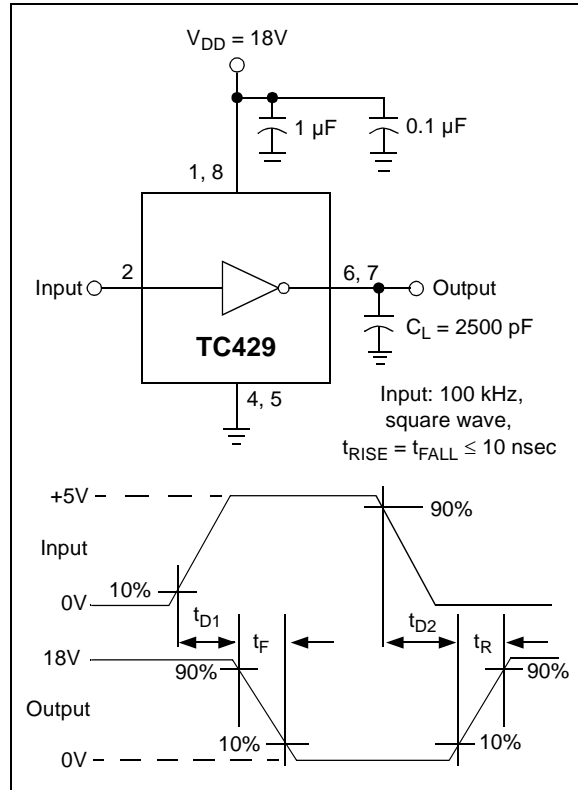
To ensure low supply impedance over a wide frequency range, a parallel capacitor combination is recommended for supply bypassing. Low-inductance ceramic disk capacitors with short lead lengths (< 0.5 in.) should be used. A 1  $\mu\text{F}$  film capacitor in parallel with one or two 0.1  $\mu\text{F}$  ceramic disk capacitors normally provides adequate bypassing.

### 4.2 Grounding

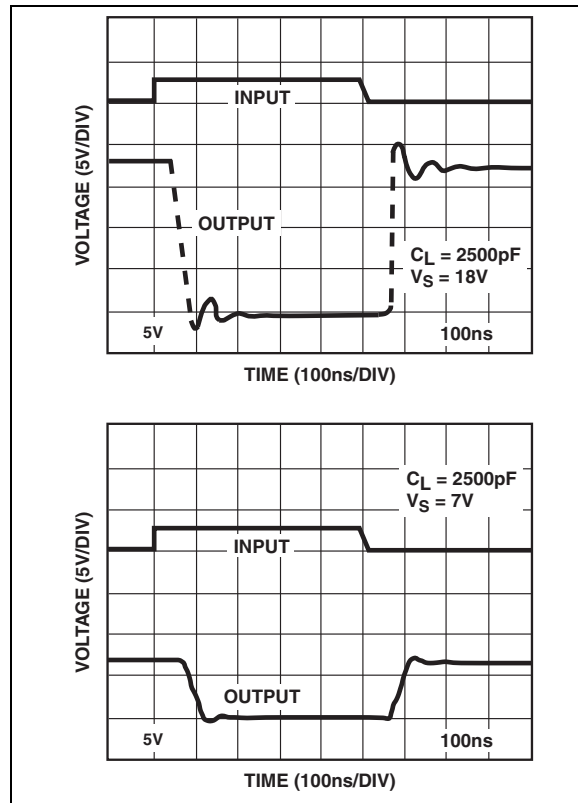
The high-current capability of the TC429 demands careful PC board layout for best performance. Since the TC429 is an inverting driver, any ground lead impedance will appear as negative feedback that can degrade switching speed. The feedback is especially noticeable with slow rise-time inputs, such as those produced by an open-collector output with resistor pull-up. The TC429 input structure includes about 300 mV of hysteresis to ensure clean transitions and freedom from oscillation, but attention to layout is still recommended.

Figure 4-3 shows the feedback effect in detail. As the TC429 input begins to go positive, the output goes negative and several amperes of current flow in the ground lead. A PC trace resistance of as little as 0.05 $\Omega$  can produce hundreds of millivolts at the TC429 ground pins. If the driving logic is referenced to power ground, the effective logic input level is reduced and oscillations may result.

To ensure optimum device performance, separate ground traces should be provided for the logic and power connections. Connecting logic ground directly to the TC429 GND pins ensures full logic drive to the input and fast output switching. Both GND pins should be connected to power ground.

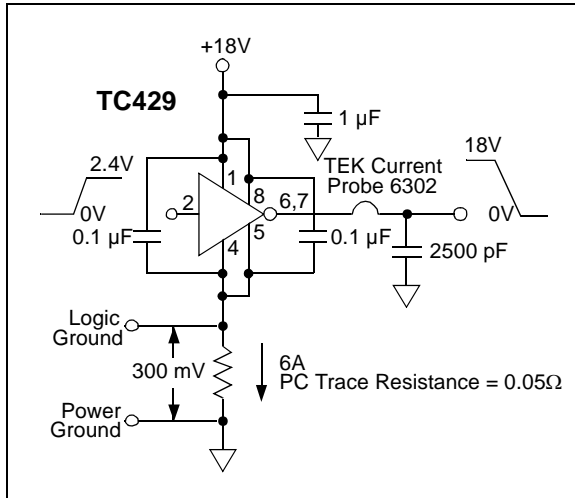


**FIGURE 4-1:** Inverting Driver Switching Time Test Circuit.



**FIGURE 4-2:** Switching Speed.





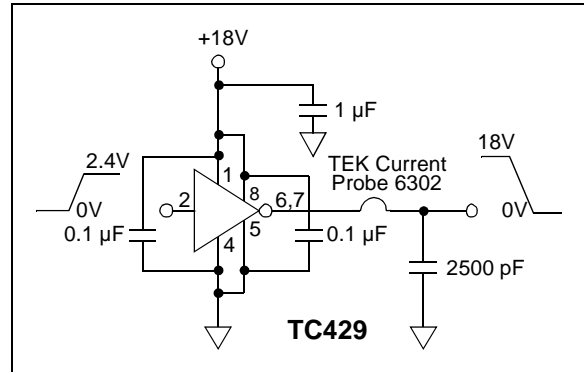
**FIGURE 4-3:** Switching Time Degradation Due To Negative Feedback.

### 4.3 Input Stage

The input voltage level changes the no-load or quiescent supply current. The N-channel MOSFET input stage transistor drives a 3 mA current source load. With a logic '1' input, the maximum quiescent supply current is 5 mA. Logic '0' input level signals reduce quiescent current to 500  $\mu$ A maximum.

The TC429 input is designed to provide 300 mV of hysteresis, providing clean transitions and minimizing output stage current spiking when changing states. Input voltage levels are approximately 1.5V, making the device TTL-compatible over the 7V to 18V operating supply range. Input pin current draw is less than 10  $\mu$ A over this range.

The TC429 can be directly driven by TL494, SG1526/1527, SG1524, SE5560 or similar switch-mode power supply integrated circuits. By off-loading the power-driving duties to the TC429, the power supply controller can operate at lower dissipation, improving performance and reliability.



**FIGURE 4-4:** Peak Output Current Test Circuit.

### 4.4 Power Dissipation

CMOS circuits usually permit the user to ignore power dissipation. Logic families such as the 4000 and 74C have outputs that can only supply a few milliamperes of current, and even shorting outputs to ground will not force enough current to destroy the device. The TC429, however, can source or sink several amperes and drive large capacitive loads at high frequency. Since the package power dissipation limit can easily be exceeded, some attention should be given to power dissipation when driving low-impedance loads and/or operating at high frequency.

The supply current versus frequency and supply current versus capacitive load characteristic curves will aid in determining power dissipation calculations. Table 4-1 lists the maximum operating frequency for several power supply voltages when driving a 2500 pF load. More accurate power dissipation figures can be obtained by summing the three components that make up the total device power dissipation.

Input signal duty cycle, power supply voltage and capacitive load influence package power dissipation. Given power dissipation and package thermal resistance, the maximum ambient operation temperature is easily calculated. The 8-pin CERDIP junction-to-ambient thermal resistance is 150°C/W. At +25°C, the package is rated at 800 mW maximum dissipation. Maximum allowable junction temperature is +150°C.

Three components make up total package power dissipation:

- Capacitive load dissipation ( $P_C$ )
- Quiescent power ( $P_Q$ )
- Transition power ( $P_T$ )

The capacitive load-caused dissipation is a direct function of frequency, capacitive load and supply voltage.

# TC429

The device capacitive load dissipation is:

## EQUATION

$$P_C = fCV_S^2$$

Where:

- f = Switching frequency
- C = Capacitive load
- V<sub>S</sub> = Supply voltage

Quiescent power dissipation depends on input signal duty cycle. A logic low input results in a low-power dissipation mode with only 0.5 mA total current drain. Logic-high signals raise the current to 5 mA maximum.

The quiescent power dissipation is:

## EQUATION

$$P_Q = V_S(D(I_H) + (1-D)I_L)$$

Where:

- I<sub>H</sub> = Quiescent current with input high (5 mA max)
- I<sub>L</sub> = Quiescent current with input low (0.5 mA max)
- D = Duty cycle

Transition power dissipation arises because the output stage N- and P-channel MOS transistors are ON simultaneously for a very short period when the output changes.

The device transition power dissipation is approximately:

## EQUATION

$$P_T = fV_S(3.3 \times 10^{-9} A \cdot Sec)$$

An example shows the relative magnitude for each item.

- C = 2500 pF
- V<sub>S</sub> = 15V
- D = 50%
- f = 200 kHz
- P<sub>D</sub> = Package power dissipation:  
= P<sub>C</sub> + P<sub>T</sub> + P<sub>Q</sub>  
= 113 mW + 10 mW + 41 mW  
= 164 mW

Maximum ambient operating temperature:

$$\begin{aligned} &= T_J - \theta_{JA} (P_D) \\ &= 150^\circ\text{C} - (150^\circ\text{C/W})(0.164\text{W}) \\ &= 125^\circ\text{C} \end{aligned}$$

Where:

- T<sub>J</sub> = Maximum allowable junction temperature (+150°C)
- θ<sub>JA</sub> = Junction-to-ambient thermal resistance (150°C/W, CERDIP)

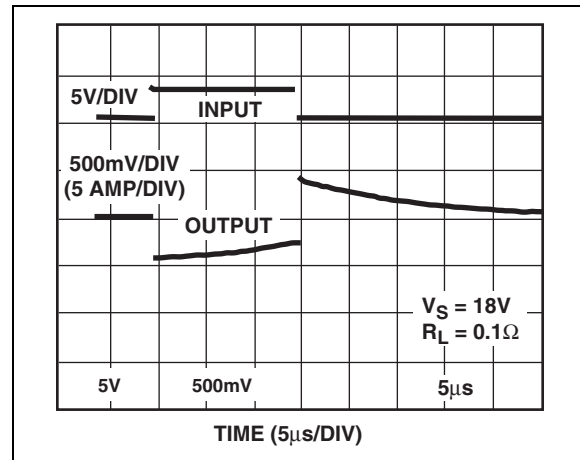
**Note:** Ambient operating temperature should not exceed +85°C for EPA or EOA devices or +125°C for MJA devices.

**TABLE 4-1: MAXIMUM OPERATING FREQUENCIES**

V <sub>S</sub>	f <sub>MAX</sub>
18V	500 kHz
15V	700 kHz
10V	1.3 MHz
5V	>2 MHz

**Conditions:**

- CERDIP Package (θ<sub>JA</sub> = 150°C/W)
- T<sub>A</sub> = +25°C
- C<sub>L</sub> = 2500 pF



**FIGURE 4-5: Peak Output Current Capability.**

## 4.5 POWER-ON OSCILLATION

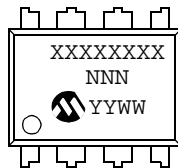
**Note:** It is extremely important that all MOSFET driver applications be evaluated for the possibility of having high-power oscillations occur during the power-on cycle.

Power-on oscillations are due to trace size, layout and component placement. A 'quick fix' for most applications that exhibit power-on oscillation problems is to place approximately 10 kΩ in series with the input of the MOSFET driver.

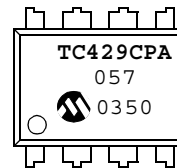
## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

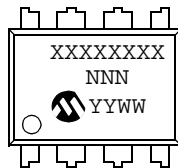
8-Lead PDIP (300 mil)



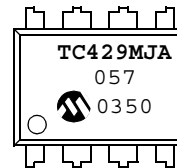
Example:



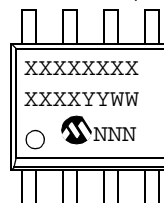
8-Lead CERDIP (300 mil)



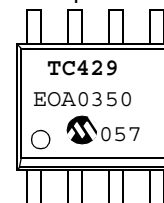
Example:



8-Lead SOIC (150 mil)



Example:



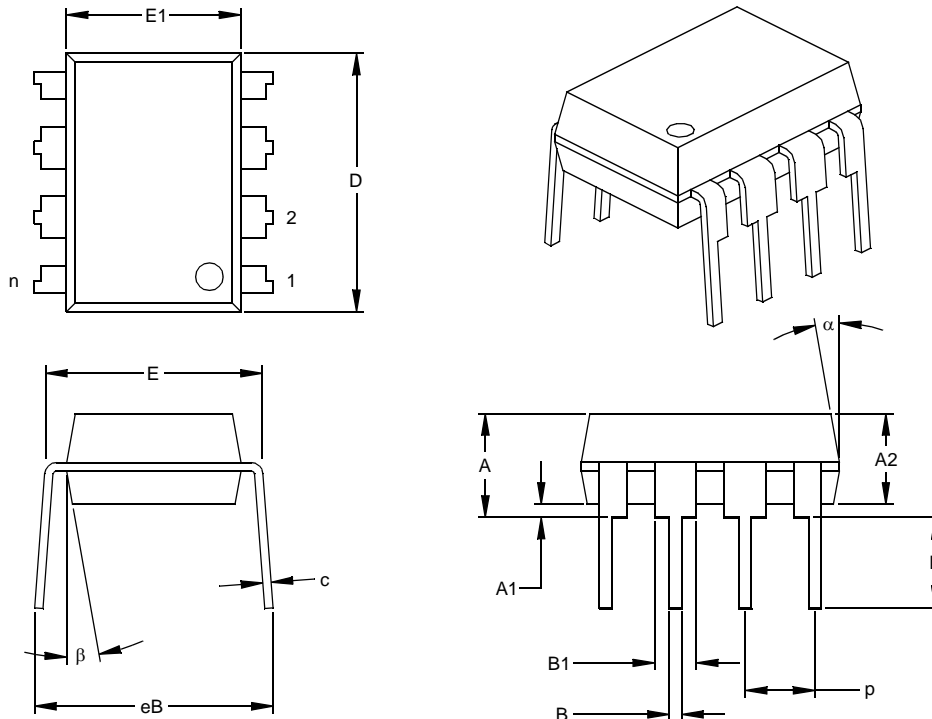
<b>Legend:</b>	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

# TC429

## 8-Lead Plastic Dual In-line (PA) – 300 mil (PDIP)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	a	5	10	15	5	10	15
Mold Draft Angle Bottom	b	5	10	15	5	10	15

\* Controlling Parameter

§ Significant Characteristic

**Notes:**

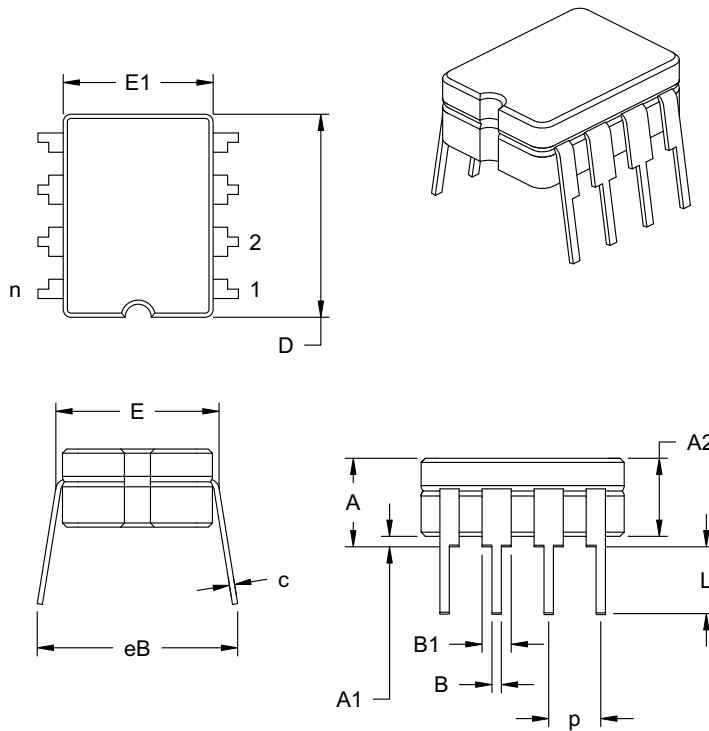
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

## 8-Lead Ceramic Dual In-line – 300 mil (CERDIP)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.180	.200	4.06	4.57	5.08
Standoff §	A1	.020	.030	.040	0.51	0.77	1.02
Shoulder to Shoulder Width	E	.290	.305	.320	7.37	7.75	8.13
Ceramic Pkg. Width	E1	.230	.265	.300	5.84	6.73	7.62
Overall Length	D	.370	.385	.400	9.40	9.78	10.16
Tip to Seating Plane	L	.125	.163	.200	3.18	4.13	5.08
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.055	.065	1.14	1.40	1.65
Lower Lead Width	B	.016	.018	.020	0.41	0.46	0.51
Overall Row Spacing	eB	.320	.360	.400	8.13	9.15	10.16

\*Controlling Parameter

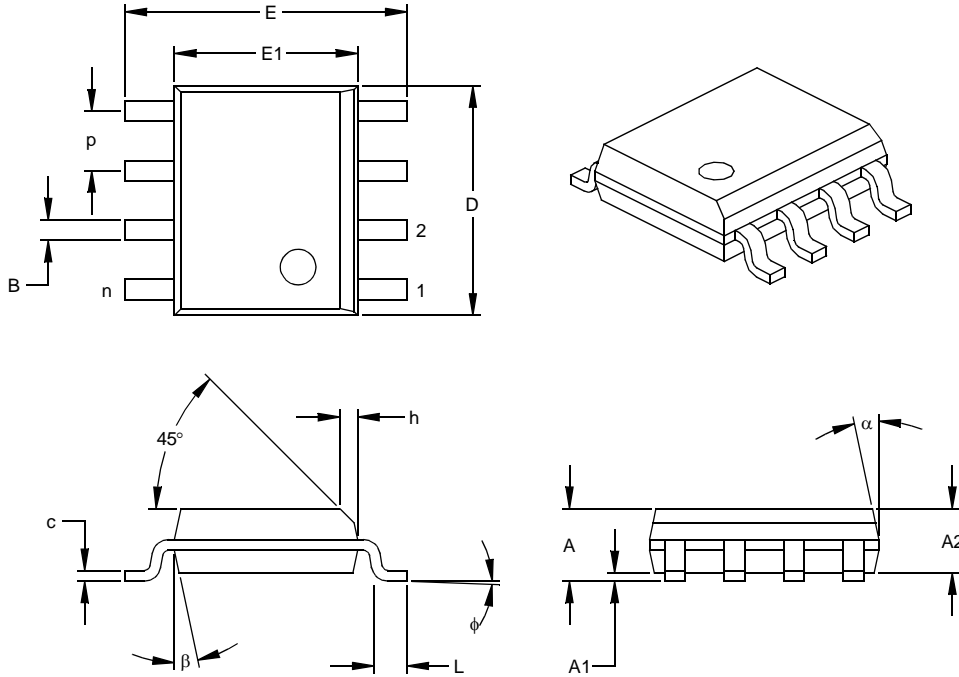
JEDEC Equivalent: MS-030

Drawing No. C04-010

# TC429

## 8-Lead Plastic Small Outline (OA) – Narrow, 150 mil (SOIC)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter  
 § Significant Characteristic

Notes:  
 Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.  
 JEDEC Equivalent: MS-012  
 Drawing No. C04-057

## 6.0 REVISION HISTORY

### Revision D (December 2012)

Added a note to each package outline drawing.

# TC429

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NOTES:



## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>
Device	Temperature Range	Package
Device:	TC429:	6A Single MOSFET Driver
Temperature Range:	C =	0°C to +70°C
	E =	-40°C to +85°C
	M =	-55°C to +125°C (CERDIP only)
Package:	JA =	Plastic CERDIP, (300 mil Body), 8-lead
	OA =	Plastic SOIC, (150 mil Body), 8-lead *
	OA713 =	Plastic SOIC, (150 mil Body), 8-lead * (Tape and Reel)
	PA =	Plastic DIP (300 mil Body), 8-lead
		* SOIC package offered in E-Temp only

**Examples:**

- a) TC429CPA: 6A Single MOSFET driver, PDIP package, 0°C to +70°C.
- b) TC429MJA: 6A Single MOSFET driver, CERDIP package, -55°C to +125°C.
- c) TC429EPA: 6A Single MOSFET driver, PDIP package, -40°C to +85°C.
- d) TC429EOA713: Tape and Reel, 6A Single MOSFET driver, SOIC package, -40°C to +85°C.

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Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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# TC429

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NOTES:

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